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MORITA et al.(10) **Pub. No.: US 2023/0232536 A1**(43) **Pub. Date: Jul. 20, 2023**(54) **ELECTRONIC MOUNTING SUBSTRATE
AND ELECTRONIC DEVICE****Publication Classification**(71) Applicant: **KYOCERA Corporation**, Kyoto-shi
(JP)(72) Inventors: **Yukio MORITA**, Kyoto-shi (JP);
Noboru KITAZUMI, Kyoto-shi (JP)(73) Assignee: **KYOCERA Corporation**, Kyoto-shi
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An electronic element mounting substrate includes a first substrate that has a first main surface, has a rectangular shape, and has a mounting portion for an electronic element on the first main surface, and a second substrate that is located on a second main surface opposite to the first main surface, is made of a carbon material, has a rectangular shape, has a third main surface facing the second main surface and a fourth main surface opposite to the third main surface, in which the third main surface or the fourth main surface has heat conduction in a longitudinal direction greater than heat conduction in a direction perpendicular to the longitudinal direction, and that has a recessed portion on the fourth main surface.

